Preliminary



CDMA 450 F-Band RF SAW Filter

- 3.8 x 3.8 x 1.4 mm Surface-mount Package
- Complies with Directive 2002/95/EC (RoHS)

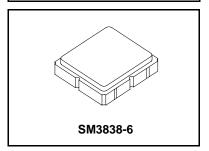


Absolute Maximum Ratings

| Rating | Value | Units |
|--|----------------|-------|
| Maximum Incident Power in Passband | +28 | dBm |
| Maximum DC voltage between any Two Terminals | 30 | VDC |
| Storage Temperature Range -40 to +85 °C | | °C |
| Suitable for Lead-free Soldering - Maximum Soldering Profile | 260°C for 30 s | |

SF1202D

465.0 MHz **SAW Filter**



Electrical Characteristics

| Characteristic | | | Notes | Min | Тур | Max | Units |
|---|------------------------|----------------|---------|-----|--------|-----|-------|
| Nominal 1 dB Cent | er Frequency | f _C | | | 465.0 | | MHz |
| Passband Insertion | Loss 462.5 to 467.5 MH | z IL | 1 | | 2.8 | 3.5 | dB |
| VSWR | 462.5 to 467.5 MH | <u>z</u> | | | 1.6:1 | 2:1 | |
| Rejection | 0.3 to 452.5 MH | Z | | 48 | 52 | | |
| | 452.5 to 457.5 MH | 7 | | 35 | 50 | | |
| 452.5 to 457.5 MHz, +15 to +40 ° C 485.0 to 507.5 MHz 507.5 to 1200 MHz | | ; | 4 2 2 | 40 | 53 | | |
| | | <u>z</u> | 1, 2, 3 | 40 | 53 | | dB |
| | | 7 | | 38 | 42 | | |
| | 1200 to 1700 MH | 7 | | 30 | 35 | | |
| | 1700 - 2000 MH | 7 | | 20 | 30 | | |
| Operating Temperature Range | | T _A | 1 | -30 | | +85 | °C |
| Impedance at f _c Source, single ended | | | | Ę | 50 ohm | | |
| Load, single ended | | | | 5 | 50 ohm | | |

| Case Style | SM3838-6 3.8 x 3.8 mm Nominal Footprint |
|--|---|
| Lid Symbolization (Y=year, WW=week, S=shift) dot=pin 1 indicator | 602, YWWS |
| Standard Reel Quantity Reel Size 7 Inch | 1000 Pieces/Reel |
| Reel Size 13 Inch | 3000 Pieces/Reel |

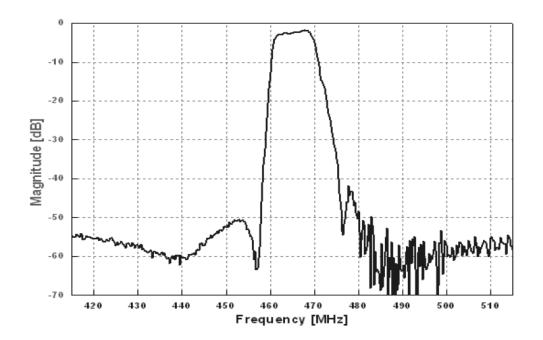
Electrical Connections

| Connection | Terminals |
|-------------|------------|
| Port 1 | 2 |
| Port 2 | 5 |
| Case Ground | All others |

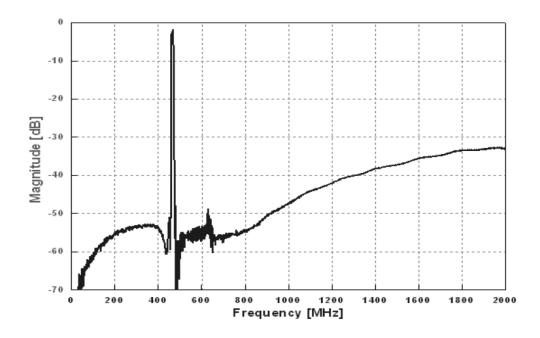


CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.

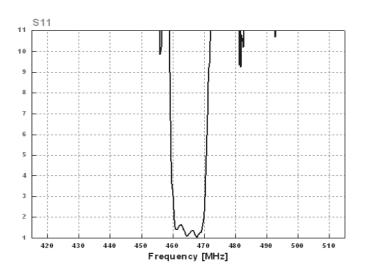
- Unless noted otherwise, all specifications apply over the operating temperature range with filter soldered to the specified demonstration board with impedance matching to 50 Ω and measured with 50 Ω network analyzer.
- Unless noted otherwise, all frequency specifications are referenced to the nominal center frequency, fc.
- Rejection is measured as attenuation below the minimum IL point in the passband. Rejection in final user application is dependent on PCB layout and external impedance matching design. See Application Note No. 42
- "LRIP" or "L" after the part number indicates "low rate initial production"
- and "ENG" or "E" indicates "engineering prototypes."
- The design, manufacturing process, and specifications of this filter are subject to change. 5.
- Either Port 1 or Port 2 may be used for either input or output in the design. However, impedances and impedance matching may vary between Port 1 and Port 2, so that the filter must always be installed in one direction per the circuit design.
- US and international patents may apply.
 RFM, stylized RFM logo, and RF Monolithics, Inc. are registered trademarks of RF Monolithics, Inc.

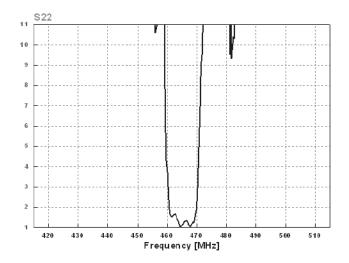


Passband Plot

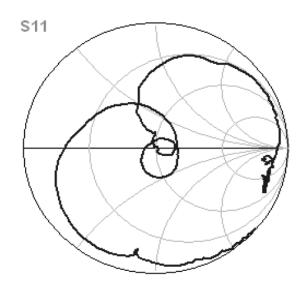


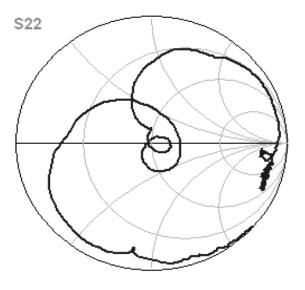
Wideband Plot





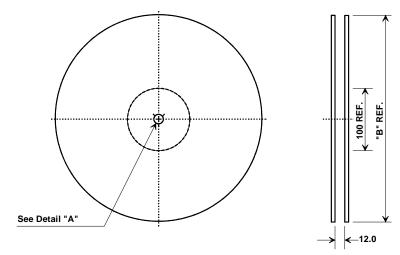
VSWR



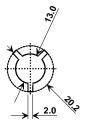


S11 and S22 Plots

Tape and Reel Specifications

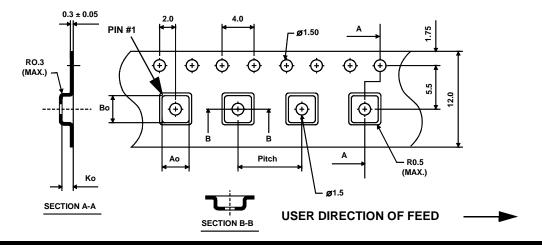


| | B " nal Size | Quantity Per Reel |
|--------|-----------------|-------------------|
| Inches | millimeters | |
| 7 | 178 | 1000 |
| 13 | 330 | 3000 |



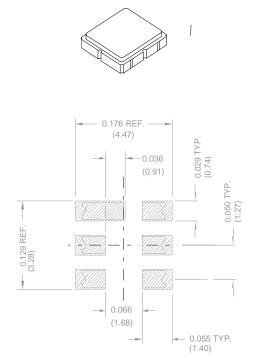
COMPONENT ORIENTATION and DIMENSIONS

| Carrier Tape Dimensions | | | |
|-------------------------|---------|--|--|
| Ao | 4.25 mm | | |
| Во | 4.25 mm | | |
| Ко | 1.30 mm | | |
| Pitch | 8.0 mm | | |
| W | 12.0 mm | | |



SM3838-6 Case

6-Terminal Ceramic Surface-Mount Case 3.8 X 3.8 mm Nominal Footprint



PCB Footprint

| | Case Dimensions | | | | | |
|-----------|-----------------|------|------|-------|--------|-------|
| Dimension | | mm | | | Inches | |
| | Min | Nom | Max | Min | Nom | Max |
| Α | 3.60 | 3.80 | 4.0 | 0.14 | 0.15 | 0.16 |
| В | 3.60 | 3.80 | 4.0 | 0.14 | 0.15 | 0.16 |
| С | 1.30 | 1.50 | 1.70 | 0.05 | 0.06 | 0.067 |
| D | 0.95 | 1.10 | 1.25 | 0.037 | 0.043 | 0.05 |
| E | 2.39 | 2.54 | 2.69 | 0.090 | 0.10 | 0.110 |
| G | 0.90 | 1.0 | 1.10 | 0.035 | 0.04 | 0.043 |
| Н | 1.90 | 2.0 | 2.10 | 0.75 | 0.08 | 0.83 |
| I | 0.50 | 0.6 | 0.70 | 0.020 | 0.024 | 0.028 |
| J | 1.70 | 1.8 | 1.90 | 0.067 | 0.07 | 0.075 |

| | Electrical Connections | | | |
|-----------------------------|------------------------|------------|--|--|
| | Connection | Terminals | | |
| Port 1 | Single Ended Input | 2 | | |
| Port 2 | Single Ended Output | 5 | | |
| | Ground | All others | | |
| Single Ended Operation Only | | | | |
| Dot indica | tes Pin 1 | | | |

| | Materials |
|-----------------------------|--|
| Solder Pad Ter- mination | Au plating 30 - 60 μinches (76.2-152 μm) over 80-200 μinches (203-508 μm) Ni. |
| Lid | Fe-Ni-Co Alloy Electroless Nickel Plate (8-11% Phosphorus) 100-200 µinches Thick |
| Body | Al ₂ O ₃ Ceramic |
| Pb Free | |

